2/12

PREPARED BY:	DATE :
7. Fuji	tani
APPROVED BY:	Mar. 9, 1995 DATE:
M.Obe	Mar. 9.1995
	<u> </u>
	DEVI
	MOI

SHARP

ELECTRONIC COMPONENTS GROUP SHARP CORPORATION

SPECIFICATION

_		/12	
SPEC	No. DG	-953054	
FILE	No.		
ISSUE	MAR.	9. 1995	
PAGE		1 / 1 1	
RIPRUŞE	NTATIVE D	IVISION	
a₽rq-ë	tę ceronic	DEVICES DIV.	
1 (11)		Think	

DEVICE SPECIFICATION FOR

PHOTO-TRANSISTOR

MODEL No.

P T 6 0 0 T

- 1. This specification sheets include the contents under the copyright of Sharp Corporation ("Sharp") Please keep **then** with reasonable care as important information. Please do not reproduce or cause anyone reproduce them without Sharp's consent.
- 2. Please obey the instructions mentioned below for actual use of this device. SHARP takes no responsibility for damage caused by improper use of the devices.
 - (1) This device is designed for general electronic equipment. Main uses of this device are as follows:
 - OA equipment AV equipment Home appliance Telecommunication equipment (Terminal) "Measuring equipment Tooling machine Computer, etc."
 - (2) Please take proper steps in order to maintain reliability and safety, in case this device is used for the uses mentioned below which require high reliability.
 - Unit concerning control and safety of a vehicle (air plane, train, automobile etc.)
 Gas leak detection breaker
 Other safety equipment, etc.
 - (3) Please do not use for the uses \square entioned below which require extremely high reliability.
 - Space equipment . Telecommunication equipment (Trunk) 'Nuclear control equipment Vedical equipment etc.

Contact a SHARP representative of sales office in advance when you intend to use SHARP devices for any applications other than those applications for general electronic equipment recommend by SHARP at (1),

CUSTOMER'S APPROVAL	DATE Mar. 9.1995 PRESENTED BY M.Abe
DATE	M, Abe Department General Manager of Engineering Dept., III
В У	Opto-Electronic Devices Div. ELECOM Group SHARP CORPORATION



PT600T Specification

I.Application

This specification applies to the outline and characteristics of Silicon photo-transistor Model No. PT600T.

This model is designed for detector of LCD back-light power control.

- 2.0utline dimensions and terminal connections
 Refer to the attached sheet, Page 3/11.
- 3.Rating and characteristics

 Refer to the attached sheet, Page 4/11.

4. Reliability

Refer to the attached sheet, Page 5/11.

S.Quality level

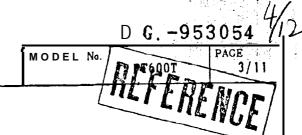
Refer to the attached sheet. Page 6/11.

6.Packing specification

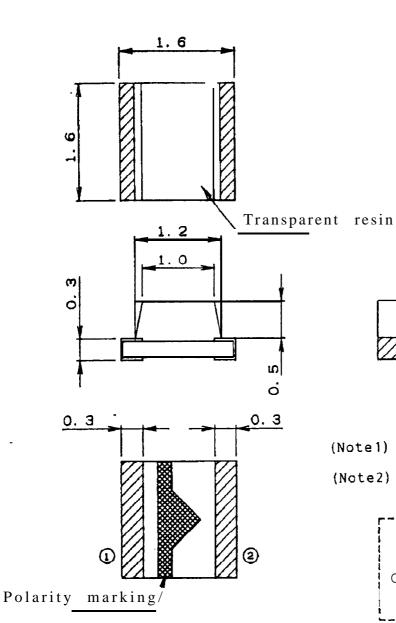
Refer to the attached sheet, Page 7/11 ~ 10/11.

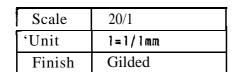
7.Notes

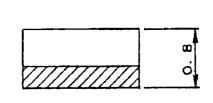
Refer to the attached sheet, Page 11/11.



2. Outline dimensions and terminal connections

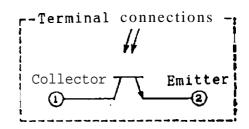






(Note1) Plating area

(Note2) General tolerances ±0.1mm



D G. -953054



SHARP

3, Rating and characteristics

3-1.Absolute maximum ratings

(Тa	=2	5t	
٠,		-	- 4	

Symbo1	Rating	Unit
Vceo	35	V
V _{ECO}	6	V
Ιc	20	mA
Pc	50	m₩
Topr	-25 ~+85	Ţ
Tstg	-25 ~+100	Ţ
Tsol	260	Ţ
	VcEO VECO Ic Pc Topr Tstg	Vc E o 35 VE C o 6 I c 20 P c 50 Topr -25 ~+85 Tstg -25 ~+100

*1 MAX. 3 seconds

3-2 .Electro-optical characteristics

(Ta=25t)

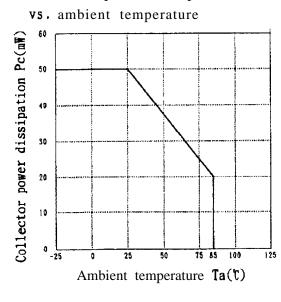
3 2 .Bicciis optical characteristics		124				
I Parameter	Symbol	Conditions *2	MIN.	TYP.	MAX.	Unit
Collector current	Ιc	$Ee=5mW/cm^2, V_{CE}=5V$	0.7	3.5	9.6	mA
Dark current	Iceo	$Ee=0, V_{CE}=20V$			0.1	μA
Collector-emitter saturation voltage	VCE (set)	$Ee=10mW/cm^2$, $I_c=0.5mA$		0.2	0.4	V
Peak sensitivity wavelength	λp			088	-	nm
Response time (Rise)	t r	$V_{cE} = 20V$, $I_c = 1 mA$		10	-	μş
Response time (Fall)	t f	$R_L = 1 kQ$		Ιo	- i	l s
Angle of half intensity	Δθ	_	_ [±60	-	٠

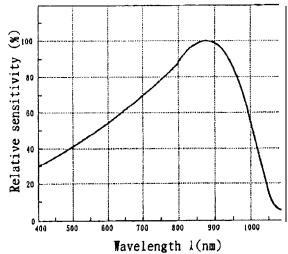
^{*} Ee: Illuminance by CIE standard light source A (tungsten lamp).

3-3.Collector power dissipation

3-4. Spectral sensitivity characteristics (TYP.)

(Ta=25t)





- FROM 51025.02 08/20/96 11:56 - 08/20 12:00 P.06/12

D G. -953054

SHARP

4. Reliability

4-1. The reliability of products shall be satisfied with items listed below.

Confidence level:90%

REFERENCE

Test Items	Reference	Test Conditions	Samples(n)	LTPD
	standards		Defective(C)	
Temperature	JIS C7021	1 cycle -25r(30min)~+100r(30min)		
cycling	A-4	20 cycle test	n=22,C=0	10%
High temp. and high	JIS C7021	Ta=+40t,90%RH,t=250h		
humidity storage	B-11		n=22,C=0	10%
High temperature	JIS C7021	Ta=+100t,t=250h		
storage	B-10		n=22,C=0	10%
Low temperature	JIS C7021	Ta=-25t, t=250h		
storage	B-12		n=22,C=0	10%
Operating test	JIS C7035	Ta=+25t, Pc=50mW, t=250h		
			n=22,C=0	10%
Soldering heat	JIS C7021	Refer to the attached sheet,		
	A-1	Page 11/11. 1 time	n=11, C=0	20%

4-2.Failure judgement criteria

No.	Parameter	Symbol F	ailure judgement criteria
1.	Collector current	Ic	L.S.L x 0.8 or U.S.L x 1.2
? .	Dark current	Icro	U.S.L x 2.0.
3.	Collector-emitter saturation voltage	Vce (**1)	U.S.L x 1.2

#U.S.L: Upper specification limit, L.S.L: Lower specification limit

FROM 61825 32 - 08 20, 96 - (1:56 - - - 98:20 - 12:9)

DG. -953054

MODEL No.

PAGE 6/11

SHARP

5. Quality level

5-l, Inspection method

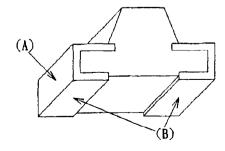
OTOUGEZITE .U ATTA9 SEGEA

A single sampling plan, normalinspection evel S-4 based on HIL-STD-105 shall be adopted,

5-2. Description of inspection and criteria

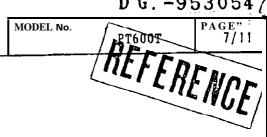
No.	Inspected items	Criteria	Defect	AQL		
1	Electro-optical characteristics	Ic CEO Not conforming to the specification Vcg (111)				
2	Taping	Product inserted in the reverse direction				
3	Tape peeling	Continuous separation of cover tape causing				
		the product to fall out	Major	0.1%		
4	Label	Model number is not printed, or misprinted	defect			
5	Mix	Another model is Mixing				
6	Quantity wanting	Quantity in package is wanting				
7	Electrode plating	Plating abnormality observed over 50% or				
		greater percentage *'		,		
8	Outline dimensions	Not conforming to the specification				
9	Label	Quantity or Lot No. is misprinted Minor				
10	Dust and flaw	Effect to the specification defect				
11	Electrode crack	0.1mm ² or greater from the product side face *1				
12	Resin flash	0.1mm or greater from the product side face				
13	Resin crack	0.3mm or greater from the product side face				
14	Polarity	Polarity is not conforming to the specification Slight 2.5%				
15	Solderbility	Could solder 50% or greater and less than 90% defect				
		out of judgement area *'				

*'Judgment area: (A) and (B)



DG.-953054

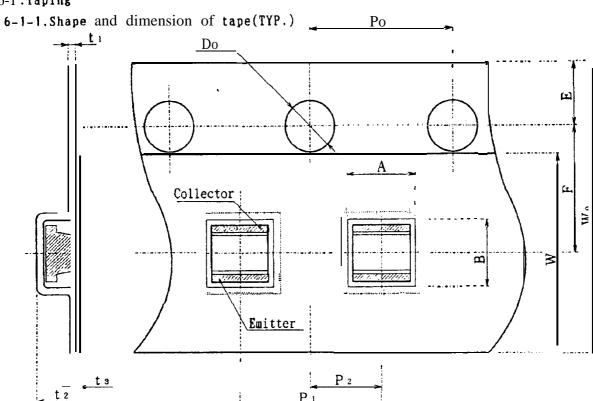
P.08/12



SHARP

6.Packing specification

6-1. Taping



Parameter		Symbol	Dimensio	Remarks		
Concave square	Vertical	A	1.9mm	1.9mm Dimension excludes corner R		
hole for part	Horizontal	В	1, 9mm	at inside bottom		
insertion	Pitch	P,	4.0mm			
Round	Diameter	Do	1.5mm			
sprocket	Pitch	Po	4.0mm	Accumulated error ±0.5mm/10 pitch		
hole	Position	Е	1.75mm	Distance between tape edge and hole center		
Center to cen-	Vert.dire	P_2	2.0mm	Center line of the concave square hole and		
ter dimension	Hori.dire	F	3.5mm	round sprocket hole		
Cover tape	Width	W,	5.5mm			
	Thickness	t ₃	0.1mm			
Carrier tape	Width	Wo	8. Omm			
	Thickness	t ₁	0.2mm			
Thickness of th	e entire					
unit		t ₂	1.2mm	With cover tape and carrier tape combined		

Pı

₩ Material: Carrier tape. ..PET, Cover tape. ..Polyester

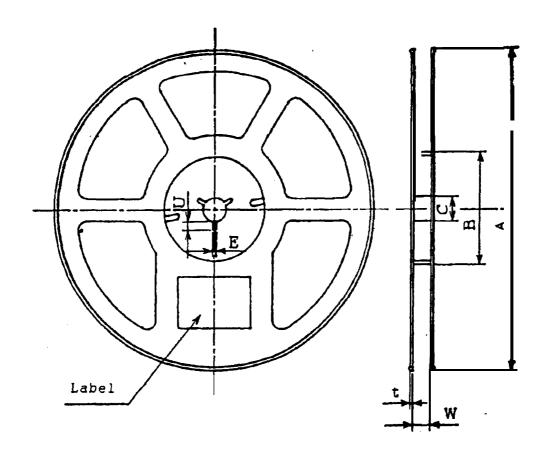
•

D G. -953054:

MODEL No. PAGE 8/11

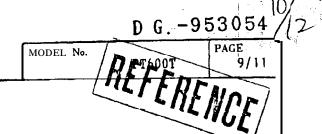
SHARP

6-1-2 .Shape and dimension of reel(TYP.)



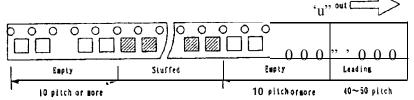
Parameter		Symbol	Dimension	Remarks	
	Diameter		А	∮178mm	
Flange	Thickness		t	1.5mm	
	Inner space direction		W	10mm	Dimension of shaft core
	External diameter		В	∮60mm	
Hub	Spindle hole diameter		С	#13mm	
	Keyslit	Width	Е	2. Omm	
	Depth		U	4.5mm	
Notation for part name etc.		Labelin	g on one si	de of flange.	
			(Part n	ame,quantit;	y.lot No.)

₩ Material: Reel ...Polystyrene

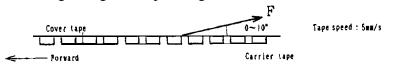


6-1-3. Taping specification

(1)Lead tape:



(2) Cover tape strength against peeling: $F=0.1\sim0.8N(\theta=10^{\circ} \text{ or less})$



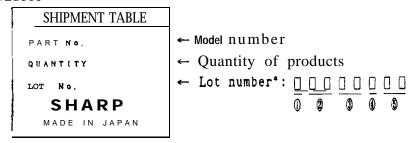
(3) Tape strength against bending:

The radius of bending circle should be 30mm or more.

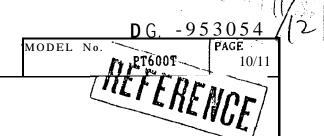
If it is less than 30mm, the cover may peel.

- (4) Jointing of tape: There should not be joint of cover tape or carrier tape.
- (5)Quantity per reel: Average 4,000pcs. per reel
- (6)Others: Apparent defect of product should not be packed and product should not upset.
 - There should not be missing above continuous three products.
 - Products should be easily taken out.
 - Products should not be attached to the cover tape at peeling.

6-2.Label

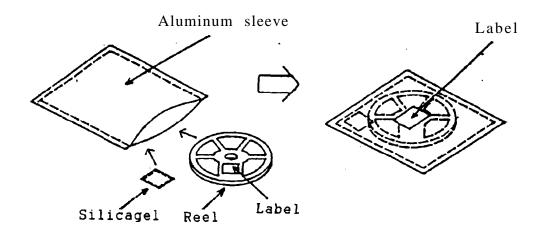


- *:Lot indication
 - ① Production plant code(to be indicated alphabetically)
 - ② Production lot(single or double figures)
 - Year of production(the last two figures of the year)
 - ♠ Month of production (to be indicated alphabetically with January corresponding to A)
 - Date of product ion(01~31)



6-3. Dampproof package

In other to avoid the absorption of humidity in transport and storage, the devices are packed in aluminum sleeve.



6-3-1. Storage conditions

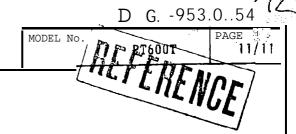
Temperature: 5 to 30°. Hum dity: ess than 60%RH

6-3-2. Treatment after opening

- **Please** make a soldering within 2 days after opening.
- ② In case the devices are not used for a long time after opening, the storage in dry box is recommendable. Or it is better to repack the devices with a desiccative by the sealer and put them in the some storage conditions as 6-3-1. Then they should be used within 2 weeks.
- ① Please make a soldering after a following baking treatment if unused term should be over the conditions of ②.

*Recommendable conditions:

Temperature: 60t. Time: 90~100 hours (in taping)



7. Notes

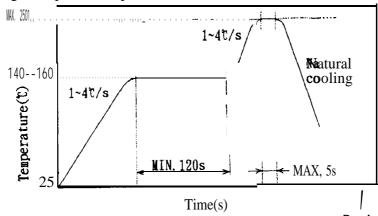
7-1. Precautions for designing

This product **is** not designed as electromagnetic and ionized-particle radiation resistant.

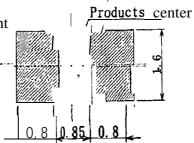
7-2.Soldering

7-2-1.Reflow soldering

- ① It is recommended no to exceed the soldering temperature and time shown below. Caused by substrate bend or the other mechanical stress during reflow soldering may happen gold wire disconnection etc. Therefore please check and study your solder reflowmachine's best condition.
- ② In case of 2 times reflow process, 2nd reflow process should be done within 8 hours after 1st reflow process.
- Reflow soldering temperature profile



Recommendable Metal Mask pattern for screen print Recommend 0.2mm to 0.3mm thickness metal mask for screen print. Caused by solder reflow condition, solder paste, substrate and the other material etc, may change solderbility. Please check and study actual solderbility before usage.



7-2-2. Manual soldering

- 1 It is recommended to keep the soldering iron temperature at 260°C (soldering iron power consumption 20W) and not to solder more than once or for over 3 seconds.
- Transform and breakdowns pay attention stress by thermal and mechanical,